

DECLARATION OF INVENTOR FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: PACKAGES FOR SEMICONDUCTOR DIE, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued therefrom.

* * * * *

Full Name of Sole or first Inventor: Todd O. Bolken

Inventor's Signature

Todd Bolken

11/3/99

Date

Residence: Meridian, Idaho

Citizenship: United States of America

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Bolken et al.
Title: PACKAGES FOR
SEMICONDUCTOR DIE
Express Mail No. EV 339208044 US
Mailed: December 9, 2003
Attorney Reference No. 6047-67518

Full Name of Second Joint Inventor, if any: Cary J. Baerlocher

Inventor's Signature

Cary T Baerlocher

11-3-99

Date

Residence: Meridian, Idaho

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Full Name of Third Joint Inventor, if any: David J. Corisis

Inventor's Signature

David J Corisis

11-12-99

Date

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Full Name of Fourth Joint Inventor, if any: Chad A. Cobbley

Inventor's Signature

Chad Cobbley

11/4/99

Date

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Citizenship: United States of America

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Bolken et al.
Title: PACKAGES FOR
SEMICONDUCTOR DIE
Express Mail No. EV 339208044 US
Mailed: December 9, 2003
Attorney Reference No. 6047-67518
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: -- Art Unit --

Todd O. Bolken, Cary J. Baerlocher, David
J. Corisis, and Chad A. Cobbley

Application No.: --

Filed: Herewith

For: PACKAGES FOR
SEMICONDUCTOR DIE

Examiner: --

POWER OF ATTORNEY BY ASSIGNEE AND
CERTIFICATE BY ASSIGNEE UNDER 37 CFR § 3.37(b)

TO THE ASSISTANT COMMISSIONER FOR PATENTS
Washington, DC 20231

Sir:

MICRON TECHNOLOGY, INC., the Assignee of the entire right, title and interest in the above-identified patent application by assignment attached hereto, hereby appoints the attorneys and agents of the firm of KLARQUIST SPARKMAN CAMPBELL LEIGH & WHINSTON, LLP, listed as follows:

Name	Reg. No.	Name	Reg. No.
BEAN, Gregory V.	36,448	MAURER, Gregory L.	43,781
BECKER, Mark L.	31,325	NOONAN, William D.	30,878
CALDWELL, Lisa M.	41,653	PETERSEN, David P.	28,106
CAMPBELL, James	19,978	POLLEY, Richard J.	28,107
DeGRANDIS, Paula A.	43,581	SCOTTI, Robert F.	39,830
GEORGE, Samuel E.	44,119	SIEGEL, Susan Alpert	43,121
GIRARD, Michael P.	38,467	SLATER, Stacey C.	36,011
JAKUBEK, Joseph T.	34,190	STEPHENS JR., Donald L.	34,022
JOHNSON, Michelle L.	36,352	STUART, John W.	24,540
JONES, Michael D.	41,879	VANDENBERG, John D.	31,312
KLARQUIST, Kenneth S.	16,445	WHINSTON, Arthur L.	19,155
KLITZKE II, Ramon A.	30,188	WIGHT, Stephen A.	37,759
HARDING, Tanya M.	42,630	WINN, Garth A.	33,220
LEIGH, James S.	20,434		

and also attorneys Michael L. Lynch (Reg. No. 30,871), Lia M. Pappas (Reg. No. 34,095), W. Eric Webostad (Reg. No. 35,406) and Charles Brantley (Reg. No. 38,086) of Micron Technology, Inc., as its attorneys with full power of

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substitution to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

The Assignee certifies that the above-identified Assignment has been reviewed and to the best of Assignee's knowledge and belief, title is in the Assignee, and a copy of the Assignment is submitted herewith.

Please direct all correspondence regarding this application to:

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MICRON TECHNOLOGY, INC.

Date: November 21, 1995 By: MLL
Name: Michael L. Lynch, Esq.
Title: Chief Patent Counsel

Attachment: Copy of Assignment; Copy of Board of Directors' Resolution